

PCB SPECIFICATIONS :

- A. MATERIAL : FR-4 TG-170 TG-150 TG-140
 B. MATERIAL FAMILY : N/A
 C. SOLDERMASK COLOR : BLUE
 D. SILKSCREEN COLOR : WHITE
 E. SURFACE FINISH : ENIG IMMERSION SILVER IMMERSION TIN
 HASL HASL (PB-FREE) GOLDEN FINGER
 F. IMPEDANCE CONTROL : NO YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
 G. THROUGH VIA : PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
 PLUG MATERIAL : SOLDERMASK NON-CONDUCTIVE EPOXY.
 H. STACK-UP : SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0.020mm	3.5
1	Top Layer 1		0.035mm	
	Dielectric 2		0.127mm	3.8
2	GND		0.035mm	
	Dielectric 1	FR-4	1.200mm	3.8
3	VDD		0.035mm	
	Dielectric 3		0.127mm	3.8
4	Bottom Layer 1		0.035mm	
	Bottom Solder	Solder Resist	0.020mm	3.5
	Bottom Overlay			

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.15mm
GAPS : 0.15mm

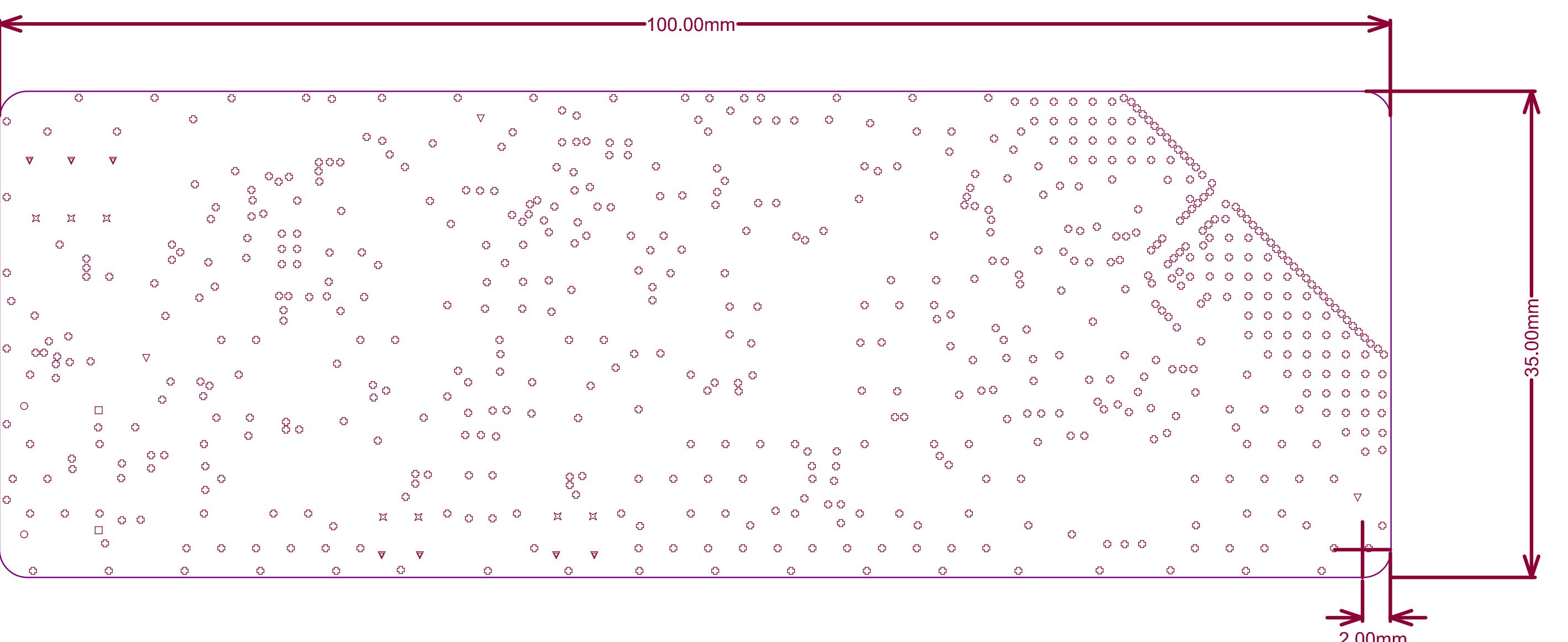
IMPEDANCE TABLE

LAYER	TRACE	SPACING	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP / Layer 3	0.6mm	0.15mm	50 ohm	NA	+/- 10%
BOT / Layer 3	0.2mm	0.15mm	NA	90 ohm	+/- 10%

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad	Pad Shape	Hole Length	Routed Path Length
+	614	7.87mil (0.20mm)	PTH	Round	Via	Rounded	-	-
□	2	23.62mil (0.60mm)	PTH	Slot	Pad	Rounded	62.99mil (1.60mm)	39.37mil (1.00mm)
○	2	23.62mil (0.60mm)	PTH	Slot	Pad	Rounded	82.68mil (2.10mm)	59.06mil (1.50mm)
☒	7	39.37mil (1.00mm)	PTH	Round	Pad	(Mixed)	-	-
▽	7	78.74mil (2.00mm)	NPTH	Round	Pad	Rounded	-	-
▽	3	118.11mil (3.00mm)	NPTH	Round	Pad	Rounded	-	-
635 Total								

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.

Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Project: BLE_SPEAKER

Layer: Drill Drawing

Variant: [No Variations]

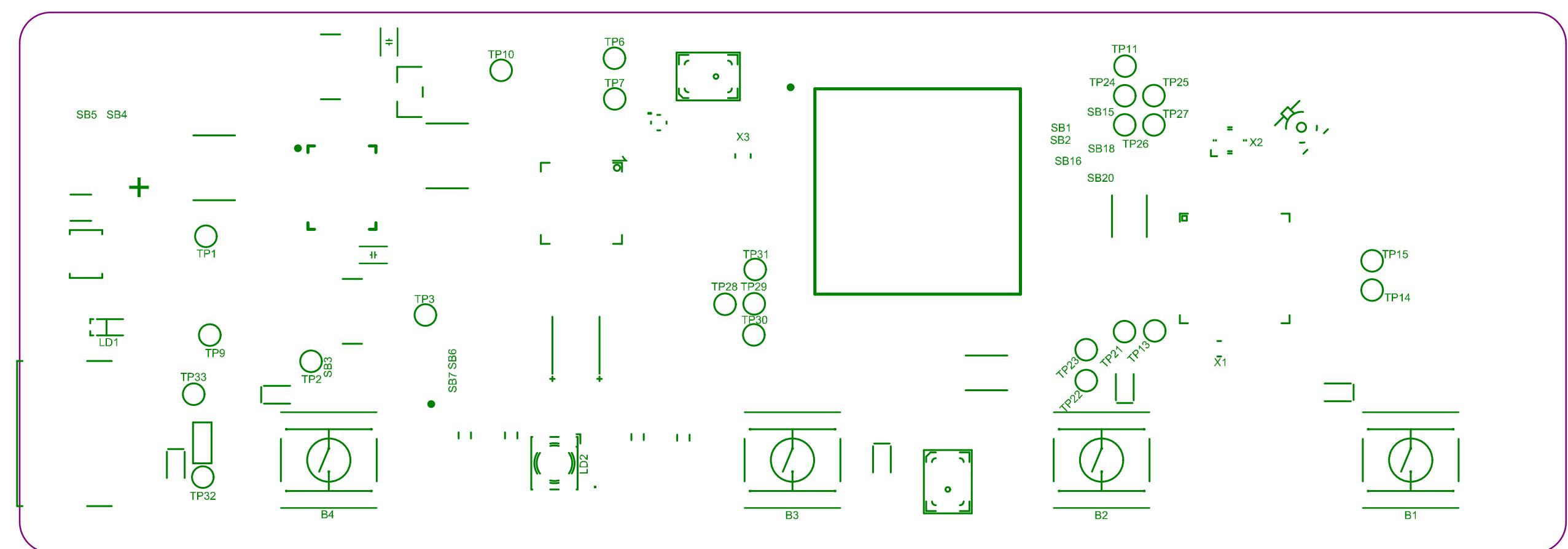
Date: 23/10/2024

Gerber: .DRL

Ref:

Rev: revB





Project: BLE_SPEAKER

Layer: Top Overlay

Variant: [No Variations]

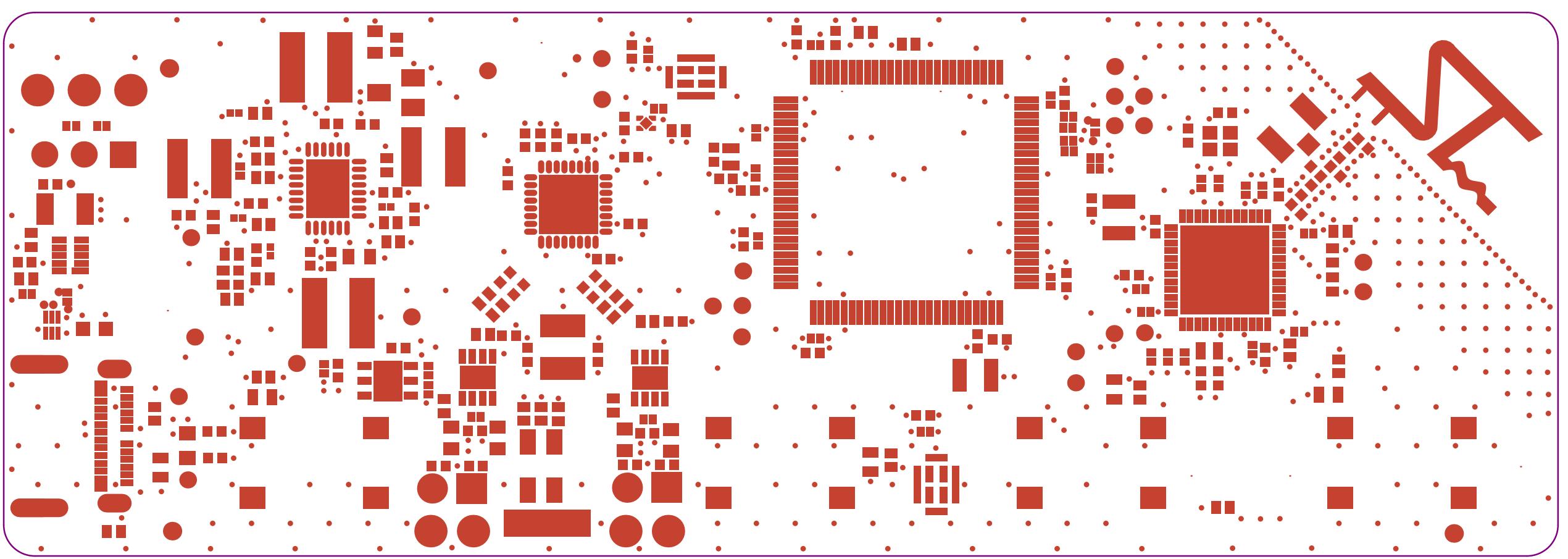
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Gerber: .GTO

Ref:

Rev: revB





Project: BLE_SPEAKER

Layer: Top Solder

Variant: [No Variations]

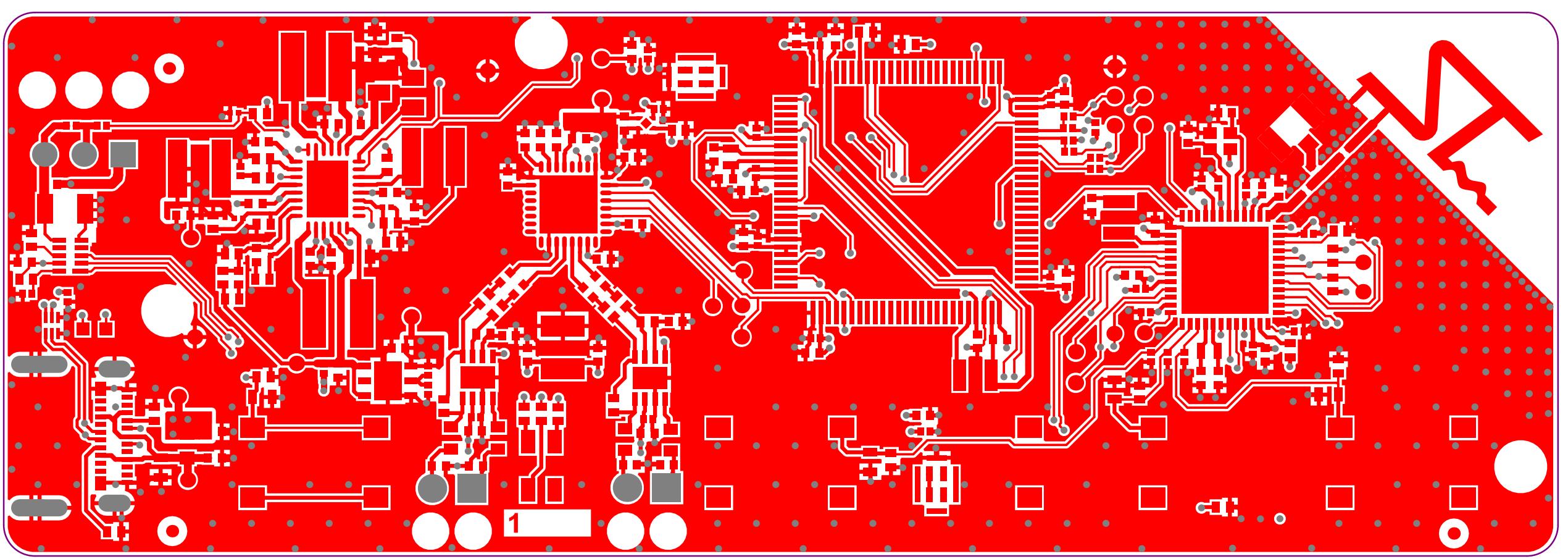
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Gerber: .GTS

Ref:

Rev: revB





Project: BLE_SPEAKER

Layer: Top Layer 1

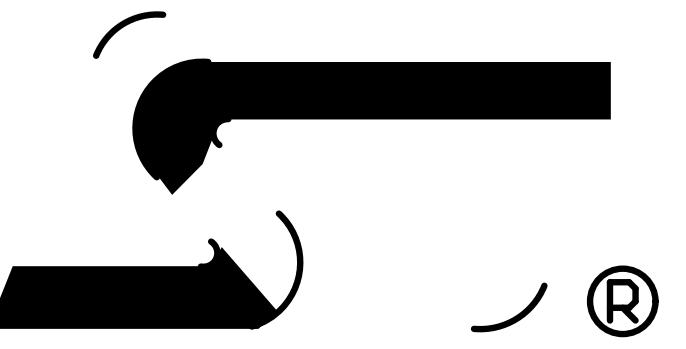
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Date: 23/10/2024

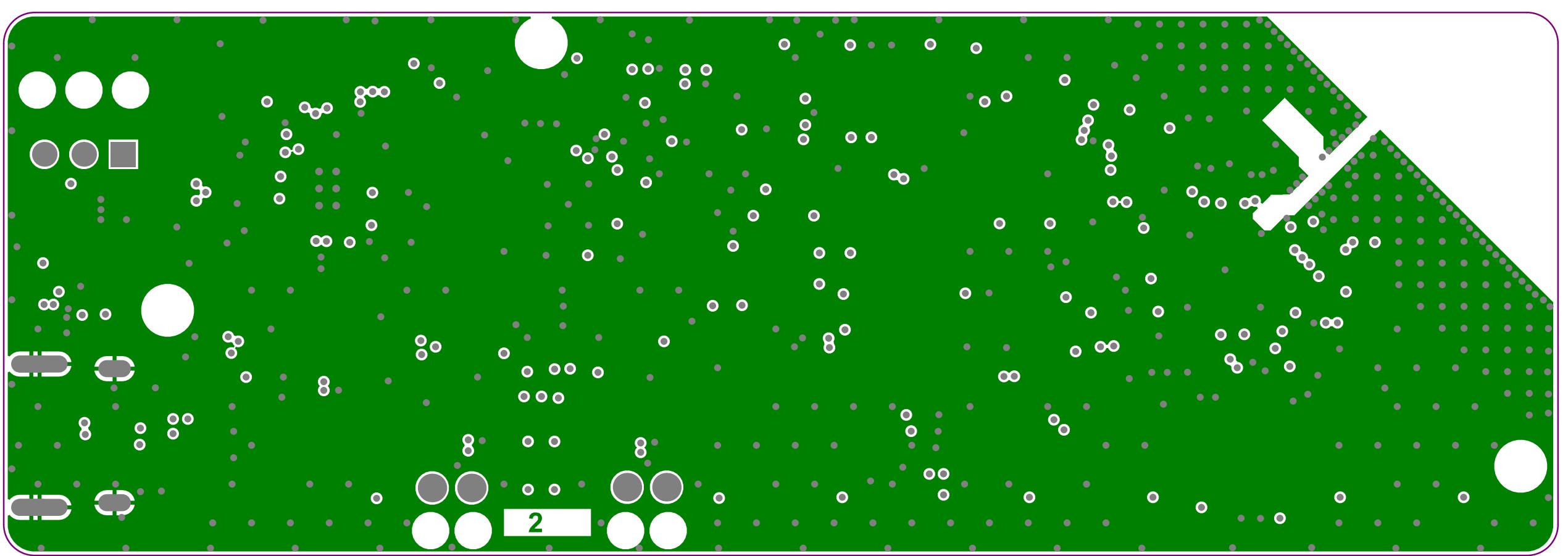
Gerber: .GTL

Ref:

Rev: revB



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Project: BLE_SPEAKER

Layer: GND

Variant: [No Variations]

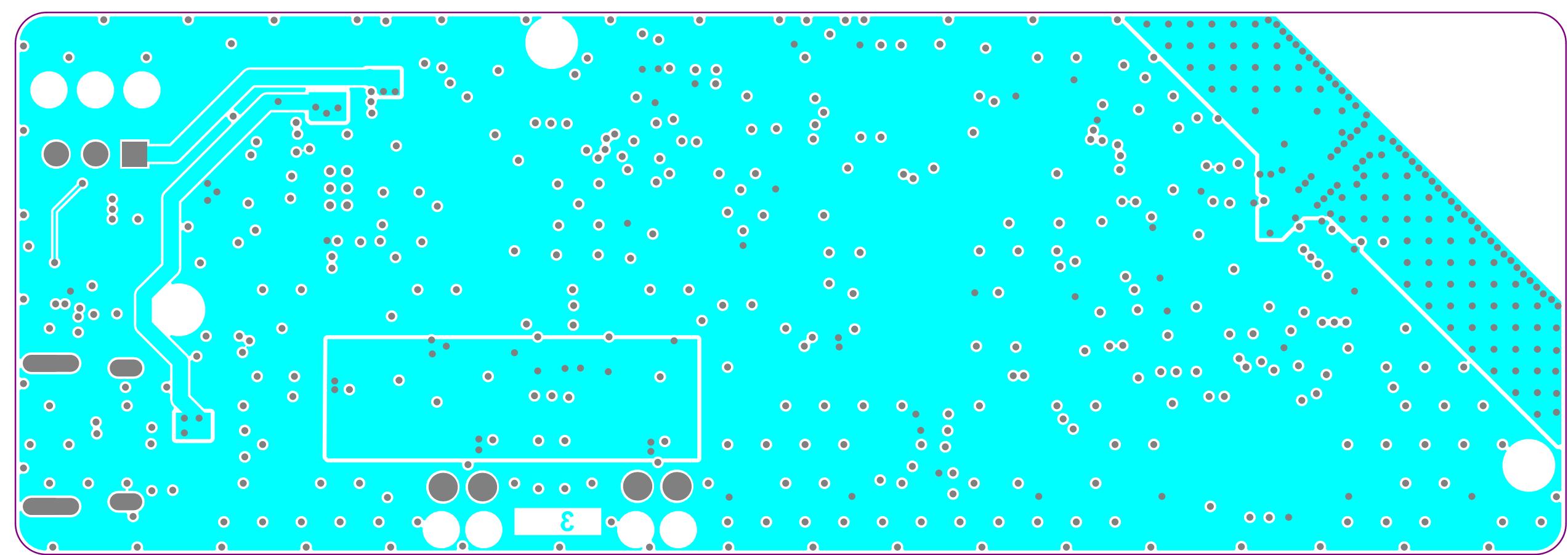
Date: 23/10/2024

Gerber: .G1

Ref:

Rev: revB





Project: BLE_SPEAKER

Layer: VDD

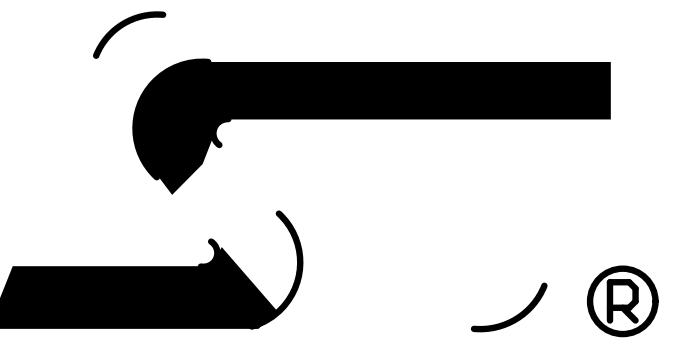
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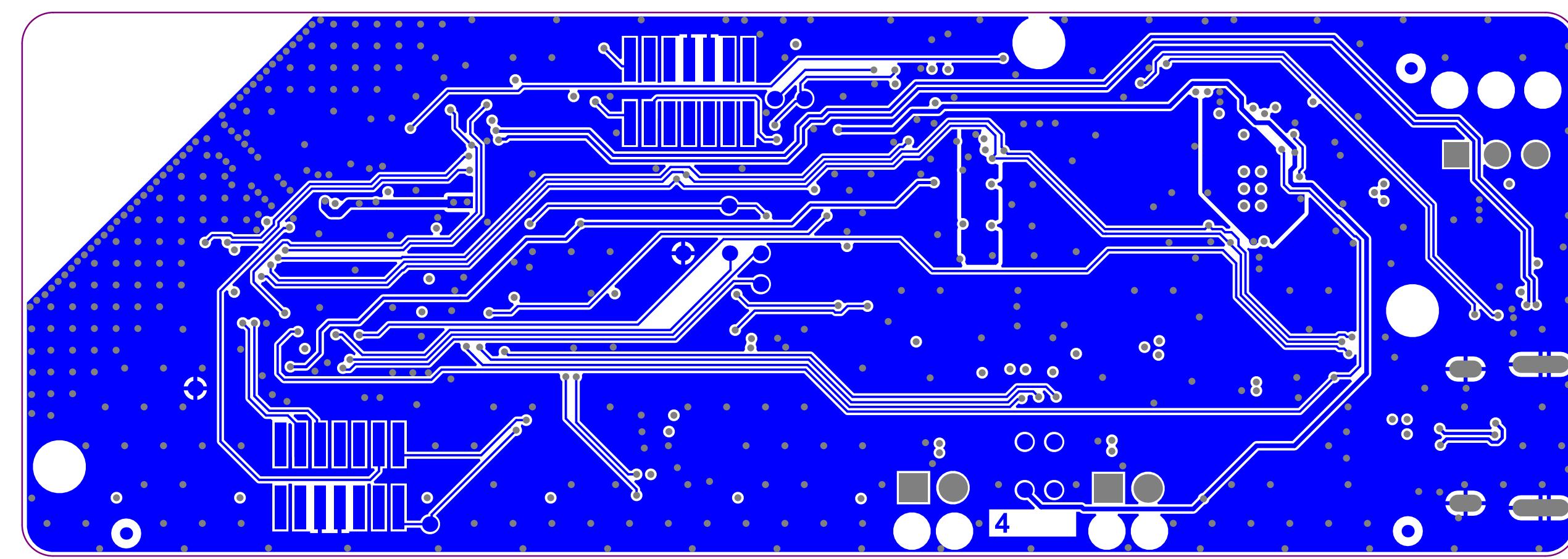
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Gerber: .G4

Ref:

Rev: revB





Project: BLE_SPEAKER

Layer: Bottom Layer 1

Variant: [No Variations]

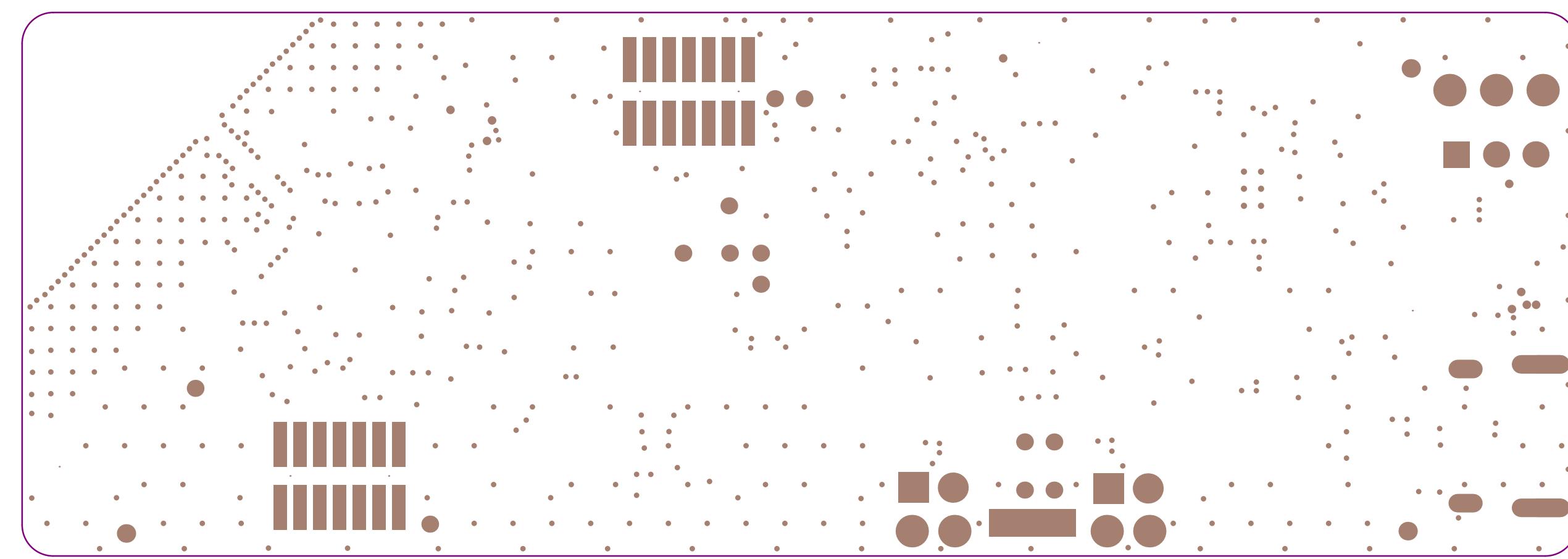
Date: 23/10/2024

Gerber:.GBL

Ref:

Rev: revB





Project: BLE_SPEAKER

Layer: Bottom Solder

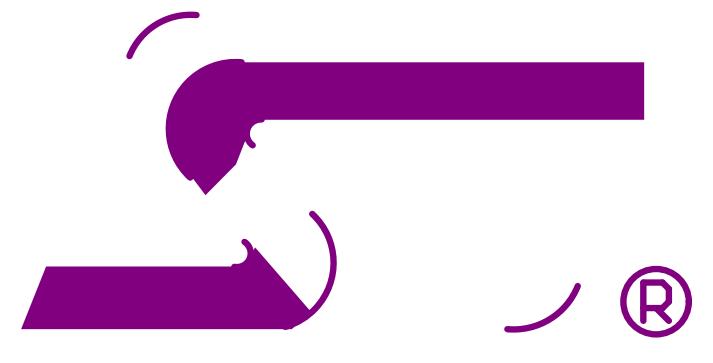
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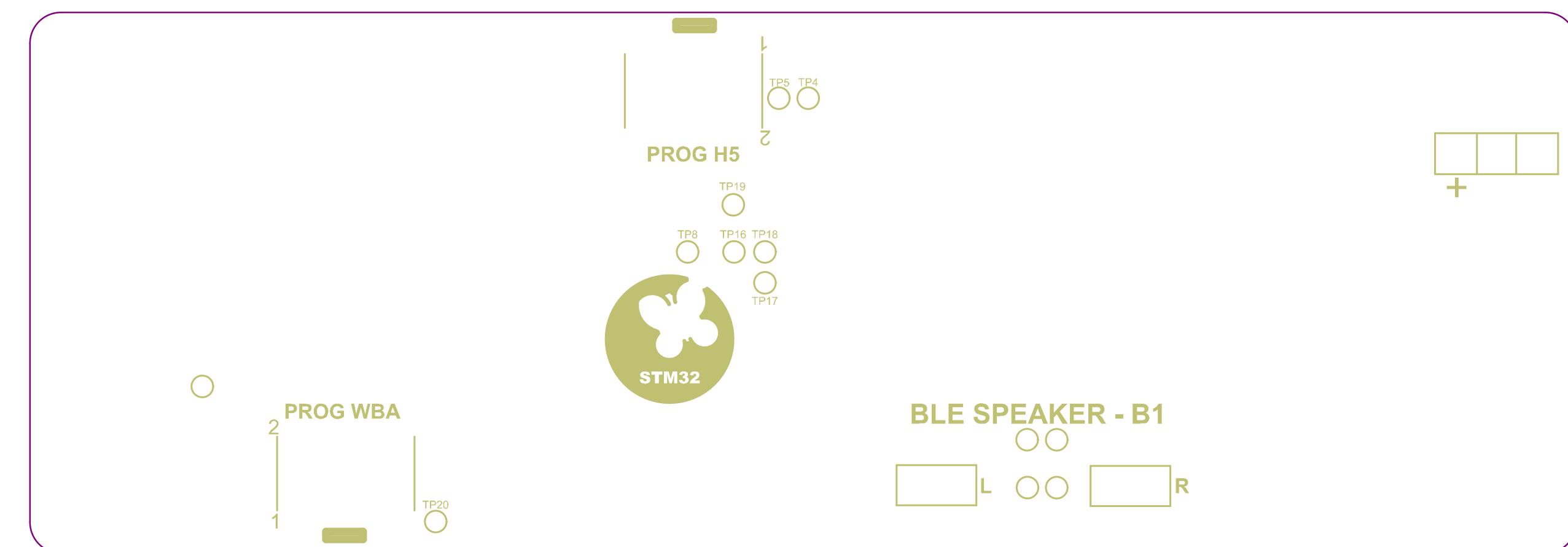
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Gerber:.GBS

Ref:

Rev: revB





Project: BLE_SPEAKER

Layer: Bottom Overlay

Variant: [No Variations]

Date: 23/10/2024

Gerber:.GBO

Ref:

Rev: revB

